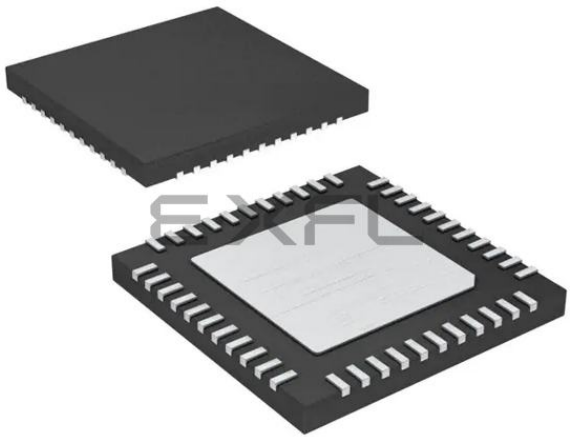
Microchip Technology - DSPIC33FJ32GP204T-I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DCI, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32gp204t-i-ml

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33F/PIC24H Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33FJ32GP204 product page of the Microchip web site (www.microchip.com).

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS70197)
- **Section 2. "CPU"** (DS70204)
- **Section 3. "Data Memory"** (DS70202)
- **Section 4. "Program Memory"** (DS70202)
- **Section 5. "Flash Programming"** (DS70191)
- **Section 6. "Interrupts** (DS70184)
- **Section 7. "Oscillator"** (DS70186)
- **Section 8. "Reset"** (DS70192)
- **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196)
- **Section 10. "I/O Ports"** (DS70193)
- **Section 11. "Timers"** (DS70205)
- **Section 12. "Input Capture"** (DS70198)
- **Section 13. "Output Compare"** (DS70209)
- **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183)
- **Section 17. "UART"** (DS70188)
- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195)
- **Section 23. "CodeGuard™ Security"** (DS70199)
- **Section 25. "Device Configuration"** (DS70194)

1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 Digital Signal Controller (DSC) devices. The dsPIC33F devices contain extensive Digital Signal Processor (DSP) functionality with a high performance 16-bit microcontroller (MCU) architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules in the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 family of devices. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-2).

Program memory addresses are always word-aligned on the lower word, and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices reserve the addresses between 0x00000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A `GOTO` instruction is programmed by the user application at 0x000000, with the actual address for the start of code at 0x000002.

dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices also have two interrupt vector tables, located from 0x000004 to 0x0000FF and 0x000100 to 0x0001FF. These vector tables allow each of the many device interrupt sources to be handled by separate Interrupt Service Routines (ISRs). A more detailed discussion of the interrupt vector tables is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-2: PROGRAM MEMORY ORGANIZATION

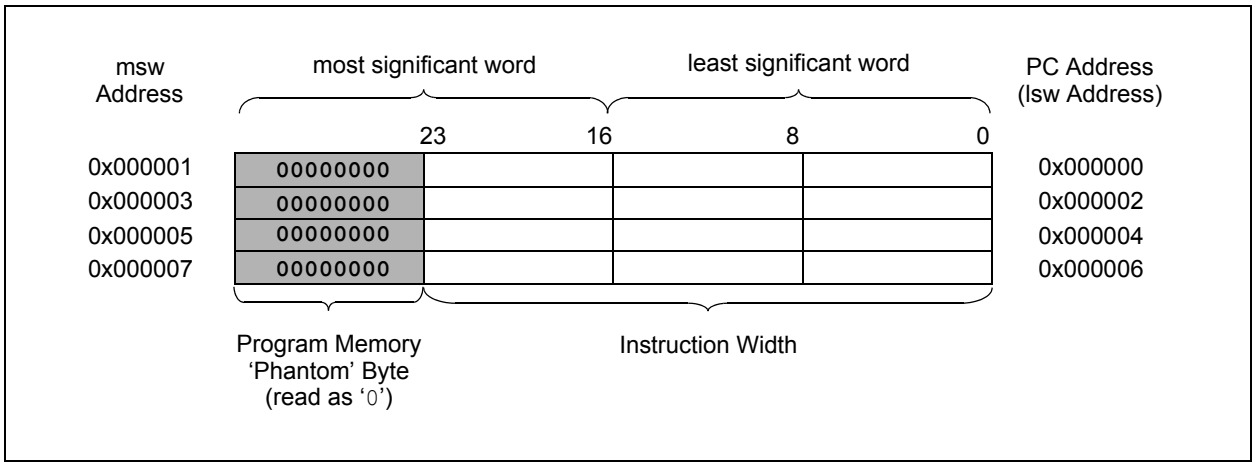
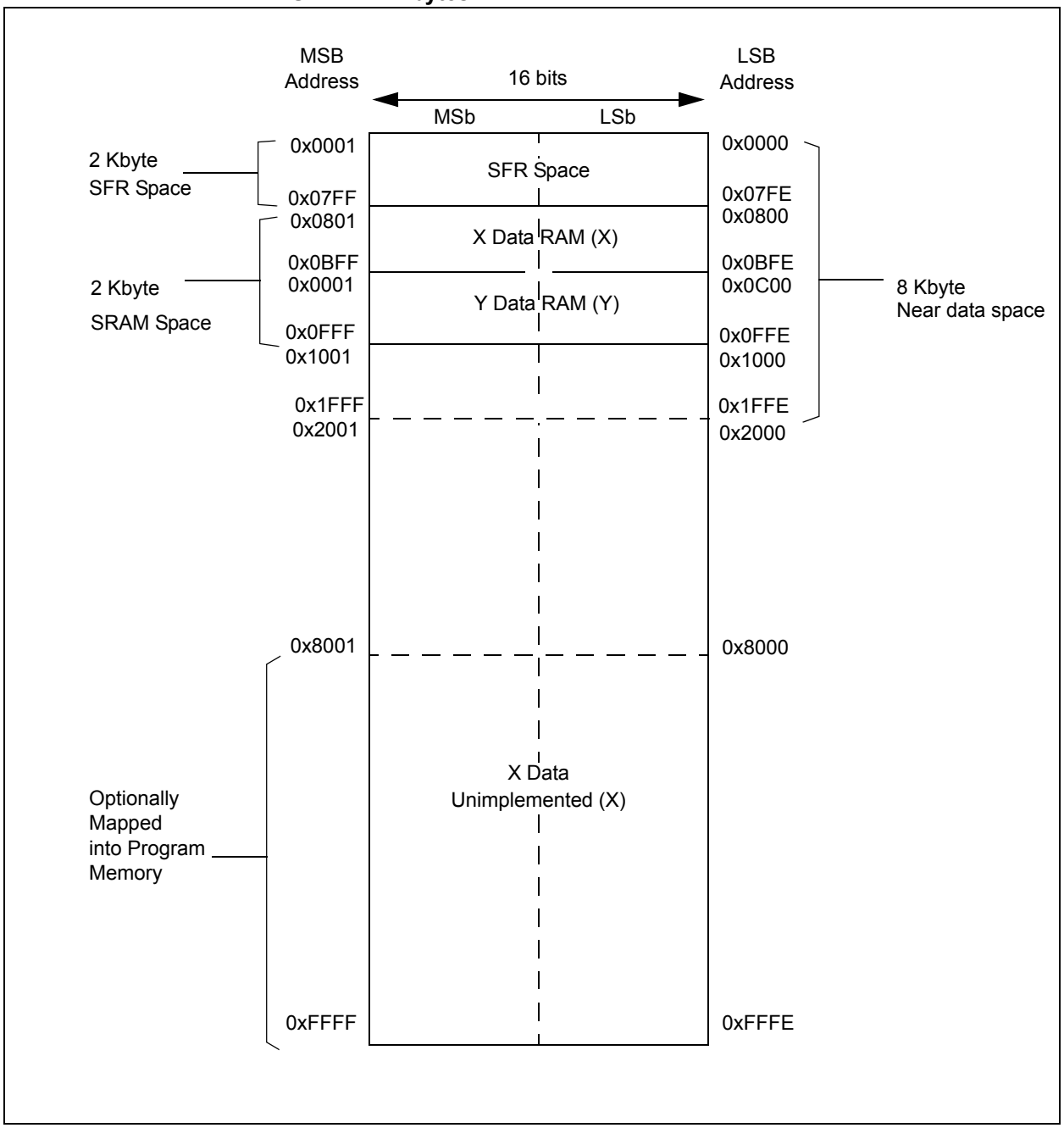


FIGURE 4-3: DATA MEMORY MAP FOR dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 DEVICES WITH 2 Kbytes RAM



EXAMPLE 5-2: LOADING THE WRITE BUFFERS

```
; Set up NVMCON for row programming operations
        MOV     #0x4001, W0             ;
        MOV     W0, NVMCON              ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
        MOV     #0x0000, W0             ;
        MOV     W0, TBLPAG              ; Initialize PM Page Boundary SFR
        MOV     #0x6000, W0             ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
        MOV     #LOW_WORD_0, W2         ;
        MOV     #HIGH_BYTE_0, W3        ;
        TBLWTL  W2, [W0]                ; Write PM low word into program latch
        TBLWTH  W3, [W0++]              ; Write PM high byte into program latch
; 1st_program_word
        MOV     #LOW_WORD_1, W2         ;
        MOV     #HIGH_BYTE_1, W3        ;
        TBLWTL  W2, [W0]                ; Write PM low word into program latch
        TBLWTH  W3, [W0++]              ; Write PM high byte into program latch
;  2nd_program_word
        MOV     #LOW_WORD_2, W2         ;
        MOV     #HIGH_BYTE_2, W3        ;
        TBLWTL  W2, [W0]                ; Write PM low word into program latch
        TBLWTH  W3, [W0++]              ; Write PM high byte into program latch
        •
        •
        •
; 63rd_program_word
        MOV     #LOW_WORD_31, W2        ;
        MOV     #HIGH_BYTE_31, W3       ;
        TBLWTL  W2, [W0]                ; Write PM low word into program latch
        TBLWTH  W3, [W0++]              ; Write PM high byte into program latch
```

EXAMPLE 5-3: INITIATING A PROGRAMMING SEQUENCE

```
        DISI    #5                      ; Block all interrupts with priority <7
                                        ; for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY              ; Write the 55 key
        MOV     #0xAA, W1               ;
        MOV     W1, NVMKEY              ; Write the AA key
        BSET    NVMCON, #WR             ; Start the erase sequence
        NOP                             ; Insert two NOPs after the
        NOP                             ; erase command is asserted
```

TABLE 6-2: OSCILLATOR PARAMETERS

Symbol	Parameter	Value
VPOR	POR threshold	1.8V nominal
TPOR	POR extension time	30 μs maximum
VBOR	BOR threshold	2.5V nominal
TBOR	BOR extension time	100 μs maximum
TPWRT	Programmable power-up time delay	0-128 ms nominal
TFSCM	Fail-Safe Clock Monitor Delay	900 μs maximum

Note: When the device exits the Reset condition (begins normal operation), the device operating parameters (voltage, frequency, temperature, etc.) must be within their operating ranges, otherwise the device may not function correctly. The user application must ensure that the delay between the time power is first applied, and the time SYSRST becomes inactive, is long enough to get all operating parameters within specification.

6.4 Power-on Reset (POR)

A Power-on Reset (POR) circuit ensures the device is reset from power-on. The POR circuit is active until VDD crosses the VPOR threshold and the delay TPOR has elapsed. The delay TPOR ensures the internal device bias circuits become stable.

The device supply voltage characteristics must meet the specified starting voltage and rise rate requirements to generate the POR. Refer to **Section 22.0 "Electrical Characteristics"** for details.

The POR status (POR) bit in the Reset Control (RCON<0>) register is set to indicate the Power-on Reset.

6.4.1 Brown-out Reset (BOR) and Power-up timer (PWRT)

The on-chip regulator has a Brown-out Reset (BOR) circuit that resets the device when the VDD is too low (VDD < VBOR) for proper device operation. The BOR circuit keeps the device in Reset until VDD crosses VBOR threshold and the delay TBOR has elapsed. The delay TBOR ensures the voltage regulator output becomes stable.

The BOR status bit in the Reset Control register (RCON<1>) is set to indicate the Brown-out Reset.

The device will not run at full speed after a BOR as the VDD should rise to acceptable levels for full-speed operation. The PWRT provides power-up time delay (TPWRT) to ensure that the system power supplies have stabilized at the appropriate levels for full-speed operation before the SYSRST is released.

The power-up timer delay (TPWRT) is programmed by the Power-on Reset Timer Value Select bits (FPWRT<2:0>) in the POR Configuration register (FPOR<2:0>), which provide eight settings (from 0 ms to 128 ms). Refer to **Section 19.0 "Special Features"** for further details.

Figure 6-3 shows the typical brown-out scenarios. The reset delay (TBOR + TPWRT) is initiated each time VDD rises above the VBOR trip point

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Use alternate vector table
0 = Use standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-3 **Unimplemented:** Read as '0'

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 8-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER(2)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN<5:0>(1)					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

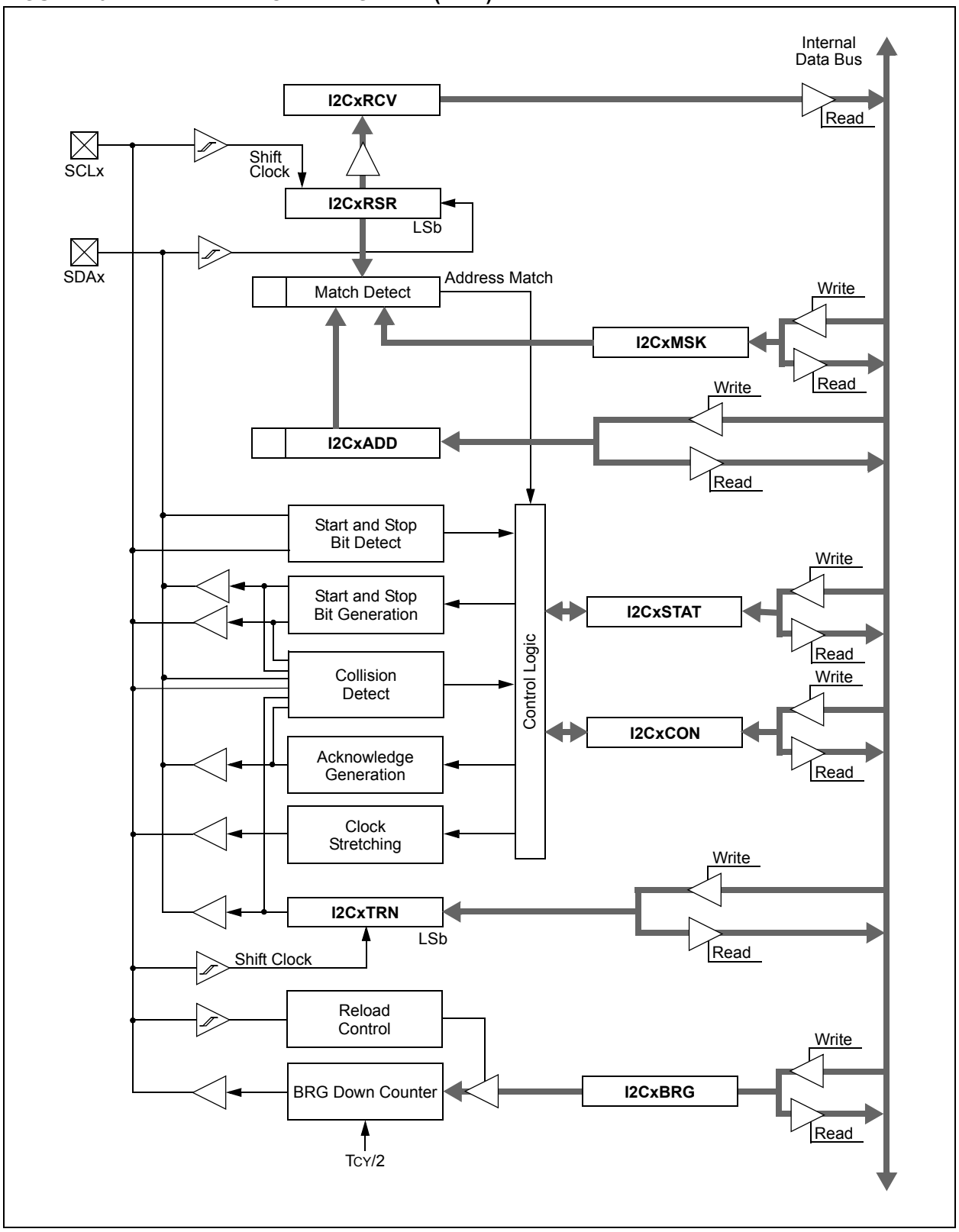
111111 = Center frequency - 0.375% (7.345 MHz)
•
•
•
100001 = Center frequency - 11.625% (6.52 MHz)
100000 = Center frequency - 12% (6.49 MHz)
011111 = Center frequency + 11.625% (8.23 MHz)
011110 = Center frequency + 11.25% (8.20 MHz)
•
•
•
000001 = Center frequency + 0.375% (7.40 MHz)
000000 = Center frequency (7.37 MHz nominal)

Note 1: The OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation and is neither characterized nor tested.

2: This register is reset only on a Power-on Reset (POR).

NOTES:

FIGURE 16-1: I²C™ BLOCK DIAGRAM (x = 1)



REGISTER 17-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0 HC	R/W-0	R-0	R-1
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN(1)	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/C-0	R-0
URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware cleared	C = Clear only bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register, and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle state is '0'
- 0 = UxTX Idle state is '1'

If IREN = 1:
- 1 = IrDA® encoded UxTX Idle state is '1'
- 0 = IrDA® encoded UxTX Idle state is '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** Transmit Break bit
- 1 = Send Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission disabled or completed

bit 10 **UTXEN:** Transmit Enable bit(1)
- 1 = Transmit enabled, UxTX pin controlled by UARTx
- 0 = Transmit disabled, any pending transmission is aborted and buffer is reset. UxTX pin controlled by port

bit 9 **UTXBF:** Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty, a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on UxRSR transfer making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on UxRSR transfer making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the UxRSR to the receive buffer. Receive buffer has one or more characters

Note 1: Refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

REGISTER 18-2: AD1CON2: ADC1 CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG<2:0>			—	—	CSCNA	CHPS<1:0>	
bit 15							bit 8

R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	—	SMPI<3:0>				BUFM	ALTS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **VCFG<2:0>:** Converter Voltage Reference Configuration bits

	ADREF+	ADREF-
000	AVDD	AVSS
001	External VREF+	AVSS
010	AVDD	External VREF-
011	External VREF+	External VREF-
1xx	AVDD	Avss

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Scan Input Selections for CH0+ during Sample A bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **CHPS<1:0>:** Select Channels Utilized bits
When AD12B = 1, CHPS<1:0> is: U-0, Unimplemented, Read as '0'
1x = Converts CH0, CH1, CH2 and CH3
01 = Converts CH0 and CH1
00 = Converts CH0

bit 7 **BUFS:** Buffer Fill Status bit (valid only when BUFM = 1)
1 = ADC is currently filling second half of buffer, user application should access data in the first half
0 = ADC is currently filling first half of buffer, user application should access data in the second half

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Sample/Convert Sequences Per Interrupt Selection bits
1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence
1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
•
•
•
0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence
0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** Buffer Fill Mode Select bit
1 = Starts filling first half of buffer on first interrupt and the second half of buffer on next interrupt
0 = Always starts filling buffer from the beginning

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses channel input selects for Sample A on first sample and Sample B on next sample
0 = Always uses channel input selects for Sample A

REGISTER 18-5: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	—	CH0SB<4:0>				
bit 15							bit 8

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA	—	—	CH0SA<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CH0NB:** Channel 0 Negative Input Select for Sample B bit
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREF-

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **CH0SB<4:0>:** Channel 0 Positive Input Select for Sample B bits

dsPIC33FJ32GP204 and dsPIC33FJ16GP304 devices only:
01100 = Channel 0 positive input is AN12
•
•
•
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

dsPIC33FJ32GP202 devices only:
01100 = Channel 0 positive input is AN12
•
•
•
01000 = Reserved
00111 = Reserved
00110 = Reserved
•
•
•
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

bit 7 **CH0NA:** Channel 0 Negative Input Select for Sample A bit
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREF-

bit 6-5 **Unimplemented:** Read as '0'

REGISTER 18-5: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER (CONTINUED)

bit 4-0 **CH0SA<4:0>:** Channel 0 Positive Input Select for Sample A bits

dsPIC33FJ32GP204 and dsPIC33FJ16GP304 devices only:

01100 = Channel 0 positive input is AN12
•
•
•
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

dsPIC33FJ32GP202 devices only:

01100 = Channel 0 positive input is AN12
•
•
•
01000 = Reserved
00111 = Reserved
00110 = Reserved
•
•
•
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

19.2 On-Chip Voltage Regulator

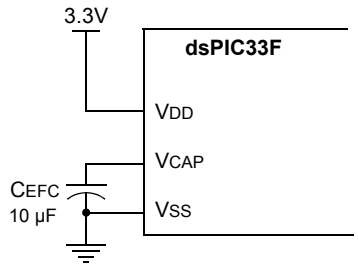
All of the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 19-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 22-13 located in **Section 22.1 "DC Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 µs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 19-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 22-13 for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

19.3 BOR: Brown-out Reset

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated voltage VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines, or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT time-out (TPWRT) will be applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

19.4 Watchdog Timer (WDT)

For dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

19.4.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler than can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TWDT) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

19.4.2 SLEEP AND IDLE MODES

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3:2>) will need to be cleared in software after the device wakes up.

19.4.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note:	If the WINDIS bit (FWDT<6>) is cleared, the CLRWDT instruction should be executed by the application software only during the last 1/4 of the WDT period. This CLRWDT window can be determined by using a timer. If a CLRWDT instruction is executed before this window, a WDT Reset occurs.

FIGURE 19-2: WDT BLOCK DIAGRAM

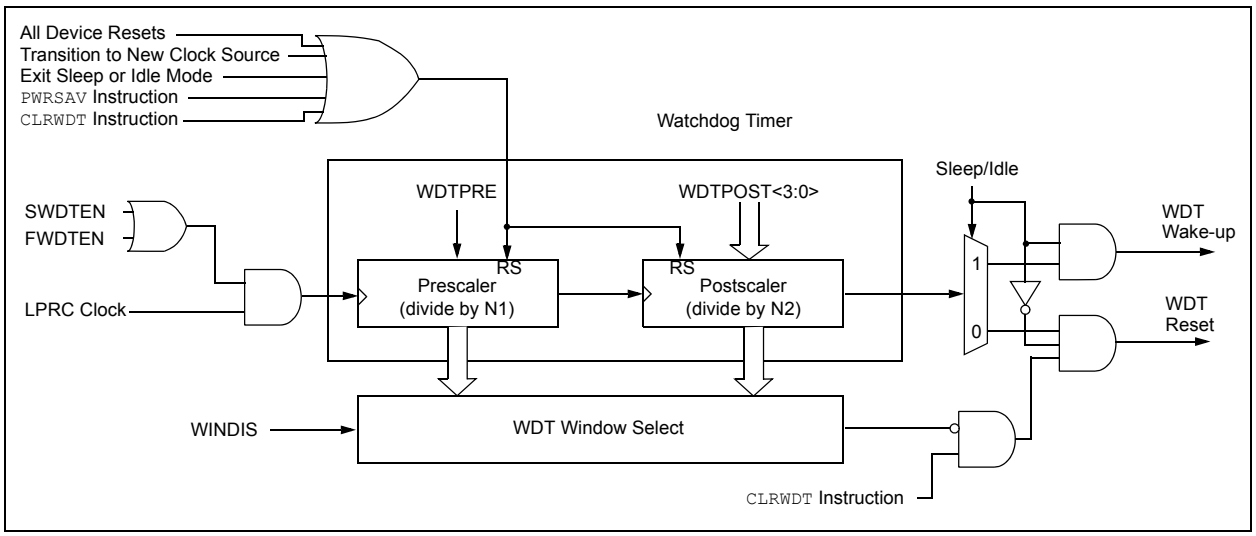


TABLE 22-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TMCL	$\overline{\text{MCLR}}$ Pulse-Width (low)(1)	2	—	—	µs	-40°C to +85°C
SY11	TPWRT	Power-up Timer Period	—	2 4 8 16 32 64 128	—	ms	-40°C to +85°C User programmable
SY12	TPOR	Power-on Reset Delay(3)	3	10	30	µs	-40°C to +85°C
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset(1)	0.68	0.72	1.2	µs	—
SY20	TWDT1	Watchdog Timer Time-out Period(1)	—	—	—	ms	See **Section 19.4 "Watchdog Timer (WDT)"** and LPRC parameter F21a (Table 22-19).
SY30	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay(1)	—	500	900	µs	-40°C to +85°C

Note 1: These parameters are characterized but not tested in manufacturing.

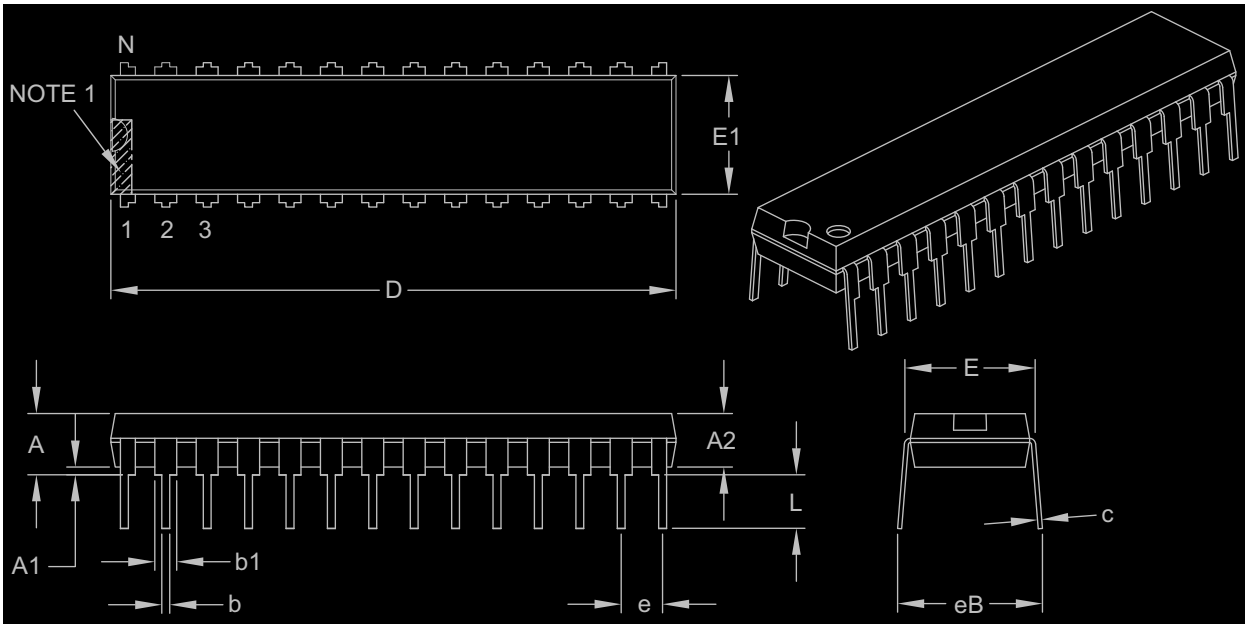
2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: These parameters are characterized, but are not tested in manufacturing.

25.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

Revision C (December 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text.

The major changes are referenced by their respective section in the following table.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Digital Signal Controllers"	Updated all pin diagrams to denote the pin voltage tolerance (see **"Pin Diagrams"**).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Added new section to the data sheet that provides guidelines on getting started with 16-bit Digital Signal Controllers.
Section 10.0 "I/O Ports"	Updated 5V tolerant status for I/O pin RB4 from Yes to No (see Table 10-1).
Section 22.0 "Electrical Characteristics"	Removed the maximum value for parameter DC12 (RAM Data Retention Voltage) in Table 22-4. Updated typical values for Operating Current (IDD) and added Note 3 in Table 22-5. Updated typical and maximum values for Idle Current (IIDLE): Core OFF Clock ON Base Current and added Note 3 in Table 22-6. Updated typical and maximum values for Power Down Current (IPD) and added Note 5 in Table 22-7. Updated typical and maximum values for Doze Current (IDOZE) and added Note 2 in Table 22-8. Added Note 3 to Table 22-12. Updated minimum value for Internal Voltage Regulator Specifications in Table 22-13. Added parameter OS42 (GM) and Notes 4, 5, and 6 to Table 22-16. Added Notes 2 and 3 to Table 22-17. Added Note 2 to Table 22-20. Added Note 2 to Table 22-21. Added Note 2 to Table 22-22. Added Note 1 to Table 22-23. Added Note 1 to Table 22-24. Added Note 3 to Table 22-32. Added Note 2 to Table 22-33. Updated typical value for parameter AD08 (ADC in operation) and added Notes 2 and 3 in Table 22-34. Updated minimum, typical, and maximum values for parameters AD23a, AD24a, AD30a, AD32a, AD32a, and AD34a, and added Notes 2 and 3 in Table 22-35. Updated minimum, typical, and maximum values for parameters AD23b, AD24b, AD30b, AD32b, AD32b, and AD34b, and added Notes 2 and 3 in Table 22-36.

NOTES: